



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



## Contact us

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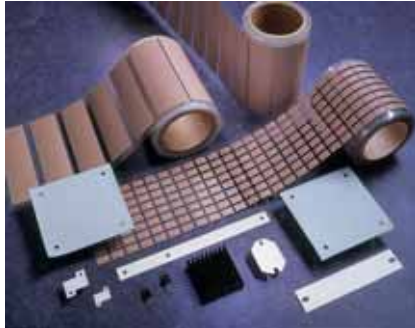
Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



### Features and Benefits

- Thermal impedance: 0.32°C-in<sup>2</sup>/W (@50 psi)
- Optimal heat transfer
- High thermal conductivity: 3.0 W /m-K



Sil-Pad A2000 is a conformable elastomer with very high thermal conductivity that acts as a thermal interface between electrical components and heat sinks. Sil-Pad A2000 is for applications where optimal heat transfer is a requirement.

This thermally conductive silicone elastomer is formulated to maximize the thermal and dielectric performance of the filler/binder matrix. The result is a grease-free, conformable material capable of meeting or exceeding the thermal and electrical requirements of high reliability electronic packaging applications.

TYPICAL PROPERTIES OF SIL-PAD A2000						
PROPERTY	IMPERIAL VALUE	METRIC VALUE	TEST METHOD			
Color	White	White	Visual			
Reinforcement Carrier	Fiberglass	Fiberglass	—			
Thickness (inch) / (mm)	0.015 to 0.020	0.381 to 0.508	ASTM D 374			
Hardness (Shore A)	90	90	ASTM D 2240			
Heat Capacity (J/g-K)	1.0	1.0	ASTM E1269			
Continuous Use Temp (°F) / (°C)	-76 to 392	-60 to 200	—			
<b>ELECTRICAL</b>						
Dielectric Breakdown Voltage (Vac)	4000	4000	ASTM D 149			
Dielectric Constant (1000 Hz)	7.0	7.0	ASTM D 150			
Volume Resistivity (Ohm-meter)	10 <sup>11</sup>	10 <sup>11</sup>	ASTM D 257			
Flame Rating	V-O	V-O	UL94			
<b>THERMAL</b>						
Thermal Conductivity (W /m-K)	3.0	3.0	ASTM D 5470			
<b>THERMAL PERFORMANCE vs PRESSURE</b>						
	Pressure (psi)	10	25	50	100	200
TO -220 Thermal Performance (°C/W) 0.015"		2.05	1.94	1.86	1.79	1.72
Thermal Impedance (°C-in <sup>2</sup> /W) 0.015" (1)		0.53	0.40	0.32	0.28	0.26

1) The ASTM D 5470 test fixture was used. The recorded value includes interfacial thermal resistance. These values are provided for reference only. Actual application performance is directly related to the surface roughness, flatness and pressure applied.

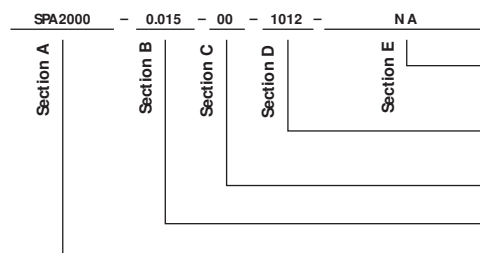
### Typical Applications Include:

- Motor drive controls
- Avionics
- High-voltage power supplies
- Power transistor / heat sink interface

### Configurations Available:

- Sheet form, die-cut parts and roll form
- With or without pressure sensitive adhesive

### Building a Part Number



### Standard Options

NA = Selected standard option. If not selecting a standard option, insert company name, drawing number, and revision level.

\_\_\_ = Standard configuration dash number, 1012 = 10" x 12" sheets, 10/250 = 10" x 250' rolls, or 00 = custom configuration

AC = Adhesive, one side  
00 = No adhesive

Standard thicknesses available: 0.015", 0.020"

SPA2000 = Sil-Pad A2000 Material

Note: To build a part number, visit our website at [www.bergquistcompany.com](http://www.bergquistcompany.com).

Sil-Pad®: U.S. Patents 4,574,879; 4,602,125; 4,602,678; 4,685,987; 4,842,911 and others